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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Applicant: Suresh Balasuramanian, et al. Docket Number: TI-36690

Serial No.: 10/717,551 Art Unit: 2815

Filed: 11/21/03 Examiner: Eugene Lee

For: High Density Memory Array

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NAME OF INVENTOR(S):	
Suresh Balasuramanian, et al.	
TITLE OF INVENTION: High Density Memory Array	
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